

Solder for Laser application

In order to reduce overheating issues against components, working time reduction, fine spot soldering as well as less populated PCB, non contacting solder is preferred.

Feature

- Best for non contact soldering of various kind(laser, hologen lamp etc)
- Low splattering under quick heating condition.
- Stable dispensing characteristic allows control of solder amount simple.
- Easy to fit best working condition.

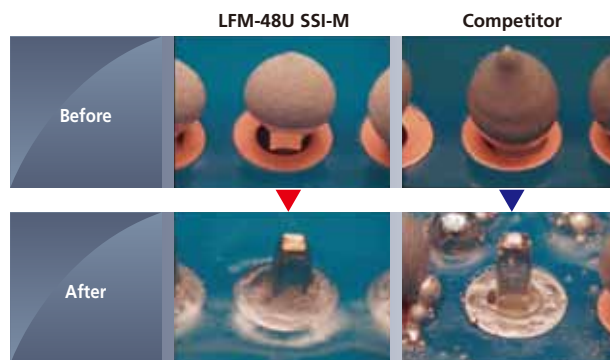
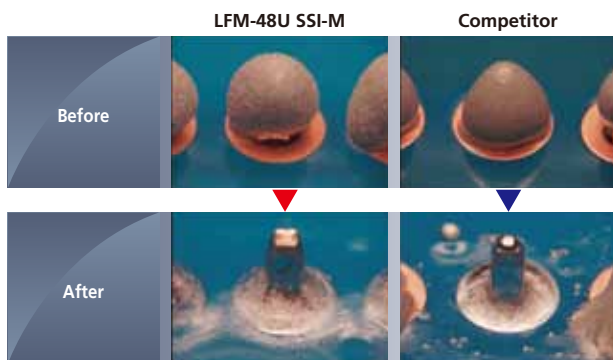
SSI-M Halogen flux solder paste for LASER / NH-LS Non Halogen solder paste for LASER

Evaluation

Wettability Validation

Diode Laser UNIX-413L II (Japan Unix)
Output 0-30W 1.5 sec

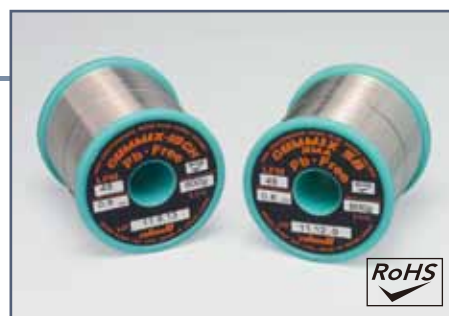
Connector ϕ 1.0mm thru-hole



Core solder for laser soldering

GUMMIX SB RMA / GUMMIX-19CH

GUMMIX SB RMA



Product Name Constituent

(Example)	LFM-48	U	NH-LS	13.0%
	Alloy Name	Powder Size	Flux name	Flux Content

Solder Paste Specification

Flux Name	Alloy Name	Alloy Composition	Powder Name: Size	Flux Content	Viscosity
NH-LS	LFM-48	Sn-3.0Ag-0.5Cu	X:25-45 μ m W:20-38 μ m U:10-28 μ m	13.0wt%	80Pa·s
SSI-M	LFM-48	Sn-3.0Ag-0.5Cu	X:25-45 μ m W:20-38 μ m U:10-28 μ m	13.0wt%	80Pa·s

※LFM-48 is sublicense product of US PAT No. 5527628.
※Standard size is 40g. Available in most of syringe types in market. Ask sales representative in your area for details.

Core solder naming configuration

(Example)	GUMMIX SB RMA	LFM-48	3.5%	1.0 ϕ
	Flux name	Alloy Name	Flux Content	Diameter

Core Solder Specification

Flux Name	Alloy Name	Flux Content	Melting Point	Diameter(mm)
GUMMIX SB RMA	LFM-48(Sn-3.0Ag-0.5Cu)	3.5%	217-220°C	0.3 0.38 0.5 0.65 0.8 1.0 1.2 1.6
GUMMIX-19CH	LFM-48(Sn-3.0Ag-0.5Cu)	3.5%	217-220°C	0.3 0.38 0.5 0.65 0.8 1.0 1.2 1.6

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